AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listing, of claims in the application:

1. (Previously Presented) A chip light emitting diode comprising:

a metal pad and a lead spaced away from each other on a printed circuit board;

a light emitting chip mounted on the metal pad;

a wire connecting the light emitting chip and the lead; and

a resin package sealing the light emitting chip and at least a part of the metal pad, lead, and the wire, the resin package having at least one curved projecting part, the at least one curved projecting part having a cross section elongated along the printed circuit board.

2. (Previously Presented) A chip light emitting diode as recited in claim 1, wherein the cross section of the curved projecting part is substantially semicircular, or substantially or partially elliptical or parabolic.

3. (Previously Presented) A chip light emitting diode as recited in claim 1, wherein the cross section of the curved projecting part is comprised of a plurality of straight lines with an angle formed between adjacent lines.

4. (Original) A chip light emitting diode as recited in claim 1, wherein at least one stepped part is formed at an outer edge of the resin package.

5. (Original) A chip light emitting diode as recited in claim 1, wherein the surface of the resin package has fine striations to scattering light emitted from the light emitting chip.

6. (Original) A chip light emitting diode as recited in claim 1, wherein the resin package has one projecting part.

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7. (Previously Presented) A chip light emitting diode as recited in claim 1,
wherein the resin package has two projecting parts which are spaced away from each
other by a predetermined interval,

wherein the predetermined interval ranges from 0.1 to 0.4 times a bottom length
of the resin package.

8-13. (Canceled)

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